

Title (en)

METHOD FOR MANUFACTURING WORKPIECE AND METHOD FOR MANUFACTURING LAMINATED CORE

Title (de)

VERFAHREN ZUR HERSTELLUNG EINES WERKSTÜCKS UND VERFAHREN ZUR HERSTELLUNG EINES LAMINIERTEN KERNS

Title (fr)

PROCÉDÉ DE FABRICATION DE PIÈCE ET PROCÉDÉ DE FABRICATION D'UN NOYAU FEUILLETÉ

Publication

**EP 3093964 A1 20161116 (EN)**

Application

**EP 16168309 A 20160504**

Priority

JP 2015097222 A 20150512

Abstract (en)

This disclosure relates to a method for manufacturing a workpiece for a segmented laminated core. This method includes (A) feeding a plate for processing drawn from a roll thereof to a progressive die and (B) stamping out a workpiece in the progressive die, the workpiece including a plurality of pieces aligned in the circumferential direction with a circumferential part. At the step (B), an overall portion configured to be each piece of the workpiece is displaced in the thickness direction of the plate for processing, with portions on both sides of the piece being fixed, to form at least one cutting line across a region configured to be the circumferential part.

IPC 8 full level

**H02K 15/02** (2006.01)

CPC (source: CN EP US)

**B21D 35/001** (2013.01 - US); **H02K 1/148** (2013.01 - EP US); **H02K 15/02** (2013.01 - CN); **H02K 15/022** (2013.01 - EP US); **H02K 15/024** (2013.01 - EP US); **H02K 15/03** (2013.01 - US); **Y10T 29/49078** (2015.01 - EP US)

Citation (applicant)

JP 4472417 B2 20100602

Citation (search report)

- [X] JP 2012005155 A 20120105 - MITSUBISHI ELECTRIC CORP
- [X] JP 2005318764 A 20051110 - MITSUI HIGH TEC
- [X] JP 2000201457 A 20000718 - MITSUI HIGH TEC
- [AD] JP 4472417 B2 20100602
- [A] US 2010052463 A1 20100304 - SAITO MASAFUMI [JP], et al
- [A] US 2012056503 A1 20120308 - CONFALONIERI SERGIO [IT]

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**EP 3093964 A1 20161116**; **EP 3093964 B1 20190717**; CA 2929174 A1 20161112; CA 2929174 C 20191001; CN 106160365 A 20161123; CN 106160365 B 20190920; JP 2016214000 A 20161215; JP 6683428 B2 20200422; PL 3093964 T3 20200131; SI 3093964 T1 20191231; US 10284062 B2 20190507; US 2016336840 A1 20161117

DOCDB simple family (application)

**EP 16168309 A 20160504**; CA 2929174 A 20160505; CN 201610304008 A 20160510; JP 2015097222 A 20150512; PL 16168309 T 20160504; SI 201630425 T 20160504; US 201615151853 A 20160511